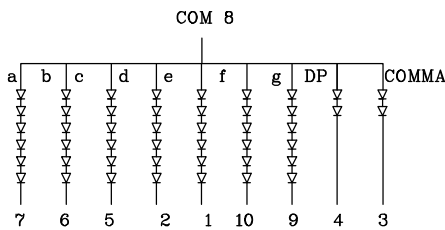


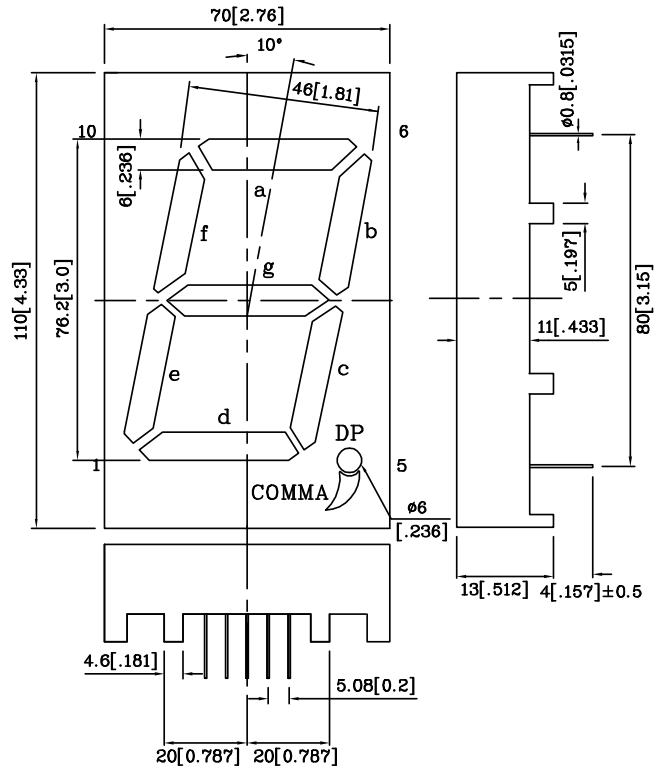
Features

- 3.0 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- CATEGORIZED FOR LUMINOUS INTENSITY.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



Notes:

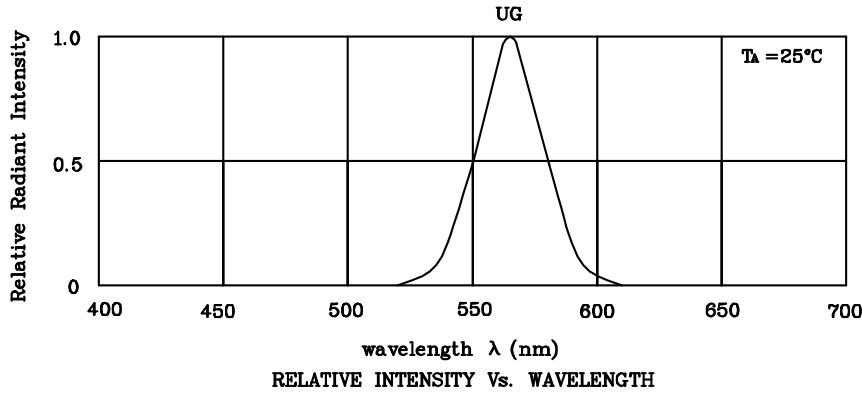
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.



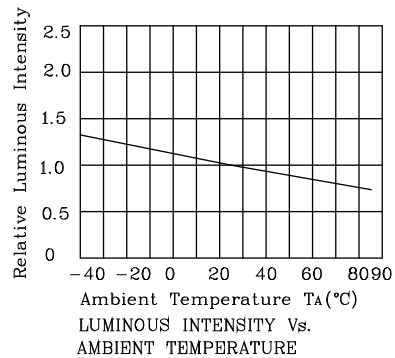
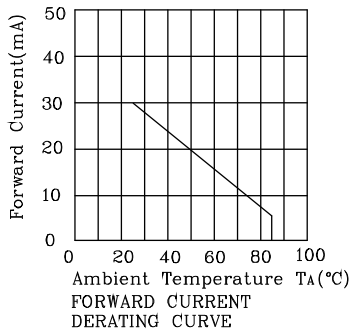
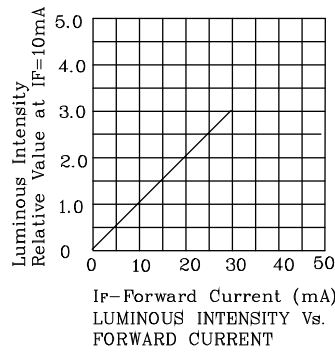
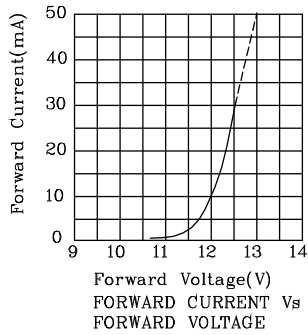
Absolute maximum ratings (TA=25°C)		UG (GaP)	Unit
Reverse Voltage Per Segment or (Dp and Comma)	VR	30 (10)	V
Forward Current Per Segment or (Dp and Comma)	IF	25 (25)	mA
Forward Current (Peak) Per Segment or (Dp and Comma) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140 (140)	mA
Power Dissipation Per Segment or (Dp and Comma)	PT	375 (125)	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics (TA=25°C)		UG (GaP)	Unit
Forward Voltage (Typ.) Per Segment or (Dp and Comma) (IF=10mA)	VF	12.0 (4.0)	V
Forward Voltage (Max.) Per Segment or (Dp and Comma) (IF=10mA)	VF	15.0 (5.0)	V
Reverse Current Per Segment or (Dp and Comma) (VR=30(10)V)	IR	10 (10)	uA
Wavelength of Peak Emission (IF=10mA)	λP	565	nm
Wavelength of Dominant Emission (IF=10mA)	λD	568	nm
Spectral Line Full Width At Half- Maximum (IF=10mA)	$\Delta\lambda$	30	nm
Capacitance (VF=0V, f=1MHz)	C	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
XDUG76A	Green	GaP	4700	18615	565	Common Anode, Rt. Hand Decimal



❖ UG



Remarks:

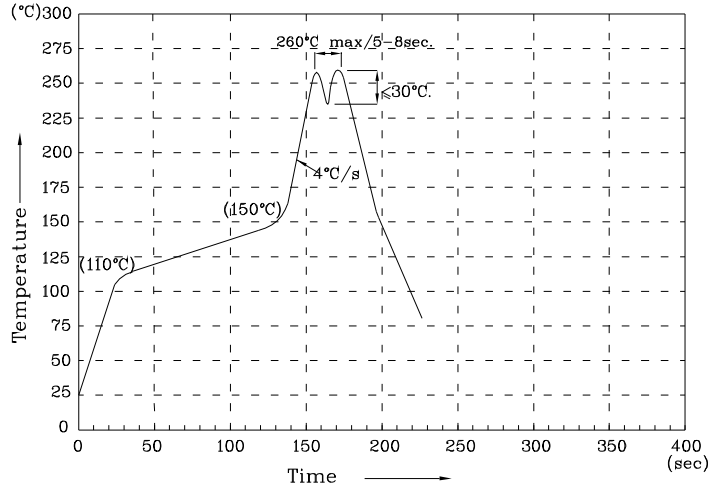
If special sorting is required (e.g. binning based on forward voltage, luminous intensity or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

XDUG76A

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.